

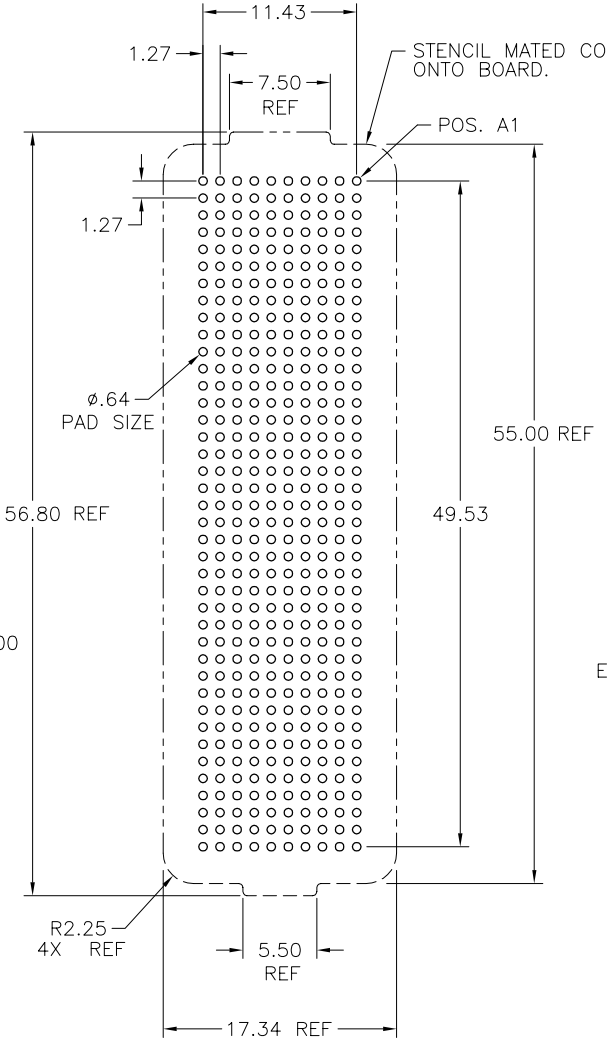
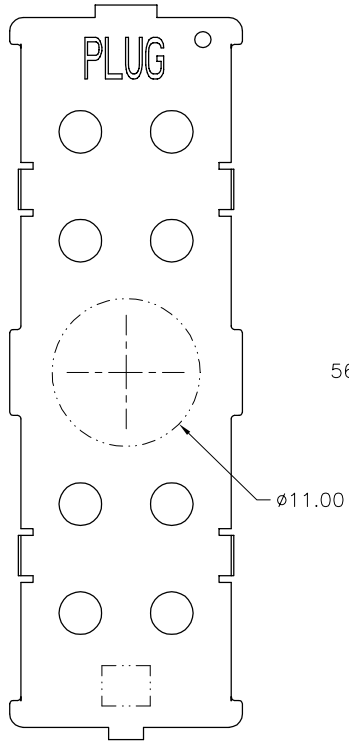
▧ .254

.54 REF

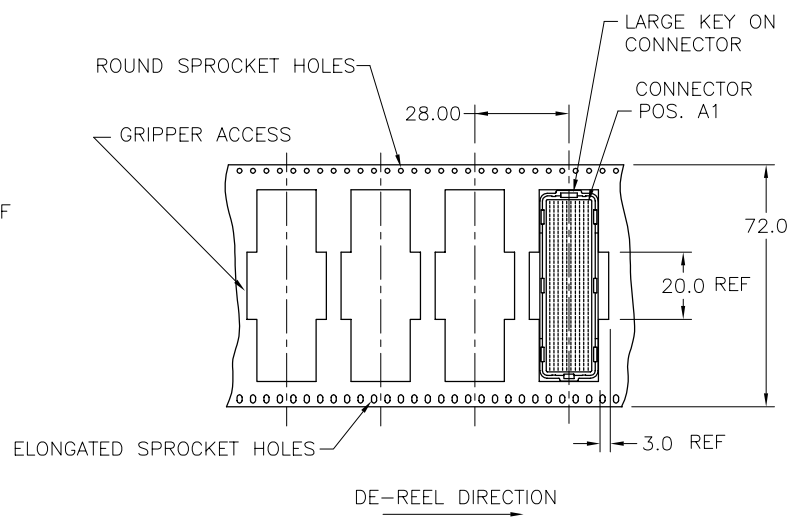
Ø.760 SOLDER BALLS  
NOTE 2

⊕ Ø.30 X Y

mat'l code		SEE NOTE 1		surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY	
ltr	ec'n no	dr	date	tolerances unless otherwise specified				⊕	title		
J	V06-0560	LP	2006/07/17	angles		X *3		mm	0mm PLUG ASSY		
-	-	-	-	line		XX *13			10 x 40 = 400 POS.		
D	V20006	DRW	1/8/02	0° ±2'		XXX *051		scale 3:1	sheet 1 of 3		
E	V20486	DRW	3/12/02	dr	D.WAUGHEN	9.18.98		FCI	size		
F	V21254	DAI	07/30/02	enfr	M.HAHN	9.18.98			A4		
G	V03-0681	DAI	06/23/03	chr	M.HAHN	9.18.98			type		
H	V04-0940	VS	10/18/04	appd	M.HAHN	9.18.98			CUSTOMER Drawing		
sheet index	revision sheet	J	J	J							
		1	2	3							



BOARD PATTERN  
SCALE 2/1



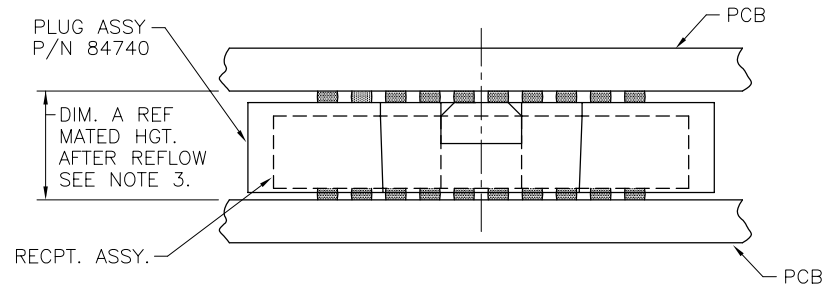
TAPE & REEL PACKAGING SCALE NONE  
PER EIA 481-3

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title
J				angles X ±3 XX ±13 0° ±2'	0mm PLUG ASSY. 10x40= 400 POS.
				dr D.WAUGHEN 9.18.98	scale 2:1
				enr M.HAHN 9.18.98	FCJ
				chr M.HAHN 9.18.98	dwg no 84740 sheet 2 of 3 size A4
				appd M.HAHN 9.18.98	type CUSTOMER Drawing
sheet index	revision sheet				

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84740-002	YES	15u" (.38um) Au OVER Ni	SnPb
84740-002LF			SnAgCu LEAD FREE (6)(7)
84740-102	YES	30u" (.76um) Au OVER Ni	SnPb
84740-102LF			SnAgCu LEAD FREE (6)(7)
84740-202	YES	SEE MATED HEIGHT TABLE (BELOW)	SnPb
84740-202LF			SnAgCu LEAD FREE (6)(7)

NOTES:

- MAT'L:**  
HOUSING: LCP  
CONTACT: COPPER ALLOY  
  
**PLATING:**  
CONTACT: (SEE TABLE ON SHEET3)  
SOLDER BALL: (SEE TABLE ON SHEET3)  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu
- SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	74221	SEE NOTE 4
6.0	74388	SEE NOTE 5
8.0	74390	SEE NOTE 5

MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi$  .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title 0mm PLUG ASSY. 10x40= 400 POS.
J				angles X *3 XX *13 XXX *051	scale 2:1
		dr	D.WAUGHEN	9.18.98	FCI dwg no 84740 sheet 3 of 3 size A4 type CUSTOMER Drawing
		enr	M.HAHN	9.18.98	
		chr	M.HAHN	9.18.98	
		appd	M.HAHN	9.18.98	
sheet index	revision sheet				